

Listing of Claims

1. (currently amended) A method of cleaning substrates, comprising the steps of:

providing a cleaning fluid;

mixing a solvent with said cleaning fluid to form a cleaning fluid mixture;

delivering said cleaning fluid mixture to a cleaning chamber;

forming a supercritical cleaning fluid from said cleaning fluid mixture in said cleaning chamber; and

contacting the substrate with said supercritical cleaning fluid in said cleaning chamber.

2. (original) The method of claim 1 wherein said cleaning fluid is carbon dioxide.

3. (original) The method of claim 1 wherein said contacting the substrate with said supercritical cleaning fluid comprises the

step of contacting the substrate with said supercritical cleaning fluid for about 5-10 minutes.

4. (original) The method of claim 3 wherein said cleaning fluid is carbon dioxide.

5. (canceled)

6. (original) The method of claim 5 wherein said cleaning fluid is carbon dioxide.

7. (original) The method of claim 1 wherein said supercritical cleaning fluid is non-conductive.

8. (original) The method of claim 1 wherein said cleaning fluid is selected from the group consisting of methane, ethane, propane, ammonia, nitric oxide, fluoromethane and difluoromethane.

9. (currently amended) The method of claim 1 [[5]] wherein said solvent is an alcohol.

10. (original) The method of claim 1 wherein each of said

substrates comprises exposed N-doped and P-doped regions.

11. (original) The method of claim 1 wherein each of said substrates comprises an exposed conductive layer.

12. (original) The method of claim 11 wherein each of said substrates comprises exposed N-doped and P-doped regions and an exposed conductive layer.

13. (currently amended) A method of cleaning a substrate to reduce galvanic corrosion of a substrate comprising N-doped and P-doped regions and a conductive layer, comprising the steps of:

providing non-supercritical cleaning fluid carbon dioxide cleaning solution;

mixing a solvent with said cleaning fluid to form a non-supercritical cleaning fluid mixture;

delivering said cleaning fluid mixture to a cleaning chamber;

forming a supercritical ~~carbon dioxide~~ from said fluid

~~carbon dioxide cleaning fluid mixture from said non-supercritical cleaning fluid mixture in said cleaning chamber; and~~

contacting the substrate with said supercritical ~~carbon dioxide~~ cleaning fluid mixture in said cleaning chamber.

14. (canceled)

15. (currently amended) The method of claim 13 wherein ~~said non-supercritical cleaning fluid~~ ~~supercritical~~ comprises carbon dioxide ~~is non-conductive.~~

16. (canceled)

17. (currently amended) A method of cleaning a substrate to reduce galvanic corrosion of exposed conductors, comprising the steps of:

providing said substrate comprising exposed metal lines;

providing a cleaning fluid selected from the group consisting of carbon dioxide, methane, ethane, propane, ammonia,

nitric oxide, fluoromethane and difluoromethane;

mixing a solvent with said cleaning fluid to form a  
cleaning fluid mixture;

delivering said cleaning fluid mixture to a cleaning  
chamber;

forming a non-conductive supercritical cleaning fluid  
from said cleaning fluid in said cleaning chamber; and

contacting the substrate with said supercritical  
cleaning fluid.

18. (canceled)

19. (original) The method of claim 17 wherein said supercritical  
cleaning fluid is non-conductive.

20. (currently amended) The method of claim 17 wherein said  
substrate comprises exposed N-doped and P-doped regions ~~and an~~  
~~exposed conductive layer.~~

21. (new) The method of claim 1, wherein the solvent is selected from the group consisting of isopropyl alcohol or other alcohols, ethylene glycol, hydrogen fluoride and ammonium hydroxide.

22. (new) The method of claim 1, wherein the substrate comprises exposed metal lines.

23. (new) The method of claim 13, wherein said non-supercritical cleaning fluid is selected from the group consisting of methane, ethane, propane, ammonia, nitric oxide, fluoromethane and difluoromethane.

24. (new) The method of claim 17, wherein said solvent is selected from the group consisting of alcohols, ethylene glycol, hydrogen fluoride and ammonium hydroxide.